The documentation and process conversion measures necessary to comply with this revision shall be completed by 2 January 1990

INCH-POUNDT

MIL-S-19500/260D 21 April 1989 SUPERSEDING MIL-S-19500/260C 28 April 1983

MILITARY SPECIFICATION

SEMICONDUCTOR DEVICE, SILICON, POWER RECTIFIER
TYPES 1N1202A, 1N1204A, 1N1206A, 1N3671A AND 1N3673A AND AR
JAN, JANTX, JANTXV, AND JANS

This specification is approved for use by all Departments and Agencies of the Department of Defense.

- SCOPE
- 1.1 <u>Scope</u>. This specification covers the detail requirements for silicon semiconductor, power rectifier diodes. Four levels of product assurance are provided for each device type as specified in MIL-S-19500.
- 1.2 Normal and reverse (AR suffix) types. Reverse and normal types are identical except: The normal types have the cathode connected to the stud and the reverse types have the anode connected to the stud. Designated values are applicable to both types.
 - 1.3 Physical dimensions. See figure 1 (DO-203AA, formerly DO-4).
 - 1.4 Maximum ratings.

Types	V _{RSM}	V _{RWM}	$I_0 \underline{1}/$ $I_C = 150^{\circ}C$	IFSM TC = 150°C t = 1/120 s	T _J and	Barometric pressure (reduced)	t _{rr}
<u> </u>	V(pk)	<u> </u>	A dc	<u>A</u>	<u>°c</u>	mmHg	μS
1N1202A	240	200	12	240	-65 to +200	N/A	10
1N1204A	480	400	12	240	-65 to +200	8	10
1N1206A	720	600	12	240	-65 to +200	16	10
1N3671A	960	800	12	240	-65 to +200	30	10
1N3673A	1200	1000	12	240	-65 to +200	54	10
•			·				ı

- 1/ Derate linearly 2 percent of I_0 per °C for $T_C = 150$ °C to $T_C = 200$ °C.
 - 1.5 Primary electrical characteristics. Reac = 2.0°C/W maximum.
 - 2. APPLICABLE DOCUMENTS
 - 2.1 Government documents.

Beneficial comments (recommendations, additions, deletions) and any pertinent data which may be of use in improving this document should be addressed to: Space and Naval Warfare Systems Command, ATTN: SPAWAR 003-114, Washington, DC 20363 by using the self-addressed Standardization Document Improvement Proposal (DD Form 1426) appearing at the end of this document or by letter.

AMSC N/A
DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

2.1.1 Specifications, standards, and handbooks. The following specifications, standards, and handbooks form a part of this document to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DODISS) and supplement thereto, cited in the solicitation (see 6.2).

SPECIFICATION

MILITARY

MIL-S-19500 - Semiconductor Devices, General Specification for.

STANDARDS

FEDERAL

FED-STD-H28 - Screw-Thread Standards for Federal Services.

MILITARY

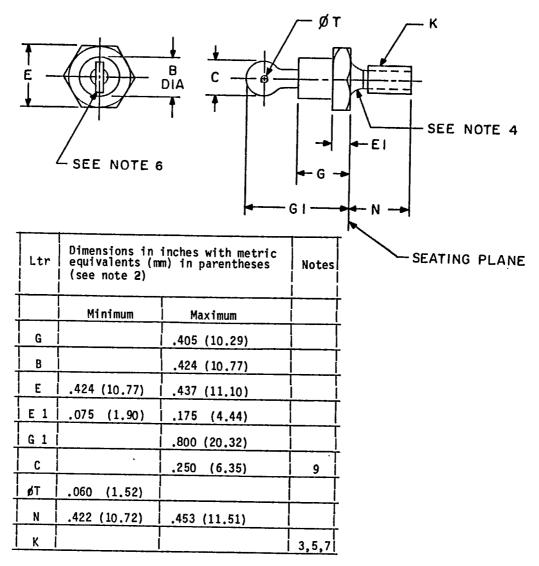
MIL-STD-750 - Test Methods for Semiconductor Devices.

(Unless otherwise indicated, copies of federal and military specifications, standards, and handbooks are available from the Naval Publications and Forms Center, (ATTN: NPODS), 5801 Tabor Avenue, Philadelphia, PA 19120-5099.)

2.2 Order of precedence. In the event of a conflict between the text of this document and the references cited herein (except for related associated detail specifications, specification sheets, or MS standards), the text of this document shall take precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

- $3.1\,$ Detail specification. The individual item requirements shall be in accordance with MIL-S-19500, and as specified herein. Lot accumulation period shall be three months in lieu of six weeks.
- 3.2 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein shall be as specified in MIL-S-19500.
- 3.3 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-S-19500, and figure 1 herein.
- 3.4 Marking. Marking shall be in accordance with MIL-S-19500, except at the option of the manufacturer, the following marking may be omitted from the body of the device:
 - a. Country of origin.
 - b. Manufacturer's identification.
- $3.5~\underline{\text{Polarity}}$. The polarity shall be indicated by a graphic symbol with the arrow pointing toward the negative end for forward bias. The reversed units shall also be marked with an R following the last digit in the type number.
 - 4. QUALITY ASSURANCE PROVISIONS
- $\frac{4.1}{\text{Sampling and inspection}}$. Sampling and inspection shall be in accordance with MIL-S-19500, and as specified herein.
- 4.2 Qualification inspection. Qualification inspection shall be in accordance with MIL-S-19500, and as specified herein. Tests in either polarity shall be sufficient to obtain qualification approval of both polarities.



NOTES:

- 1. Dimensions are in inches.
- Metric equivalents are given for general information.
- Units must not be damaged by torque of 15 inch-pounds applied to
- 10-32NF2B nut assembled on thread.
 4. Diameter of unthreaded portion .189 (4.80 mm) max and .163 (4.14 mm) min.
 5. Complete threads shall extend to within 2-1/2 threads of the seating plane.
- Angular orientation of this terminal is undefined.
- Maximum pitch diameter of plated threads shall be basic pitch diameter .169 inch (4.31 mm) reference FED-STD-H28 (Screw Thread Standards for Federal Services).
- The A.S.A. thread reference is 10-32UNF2A.
- Terminal end shape is unrestricted.
 Reversed (anode to stud) units shall be marked with an R following the last digit in the type number.

FIGURE 1. Physical dimensions.

4.3 Screening (JANS, JANTXV, and JANTX levels only). Screening shall be in accordance with MIL-S-19500 (table II) and as specified herein. The following measurements shall be made in accordance with table I herein. Devices that exceed the limits of table I herein shall not be acceptable.

Screen (see	Measure	ements
MIL-S-19500)	JANS level	JANTX and JANTXV levels
1/	Surge, see 4.3.1; Thermal response, see 4.3.2	Surge, see 4.3.1; Thermal response, see 4.3.2
4	 Not applicable 	
9	V_{F2} and I_{R1} $\underline{2}/$	V _{F2} and I _{R1} 2/
10	 MIL-STD-750, method 1038, test condition A, t = 96 hrs.	MIL-STD-750, method 1038, test condition A, t = 48 hrs.
11	V_{F2} and I_{R1} ; ΔV_{F2} = ± 0.1 $V(pk)$; ΔI_{R1} = 5 μ A dc lor 100% from the initial value, whichever is greater. Subgroup 2 of table I herein.	Subgroup 2 of table I herein, V_{F2} land I_{R1} ; ΔV_{F2} = ± 0.1 $V(pk)$; ΔI_{R1} = 5 μA dc or 100% from the linitial value, whichever is greater. $3/$
12	 Burn-in, see 4.3.3 and 4.5.1. MIL-STD-750, method 1038, test condition B.	Not applicable
13	Subgroups 2 and 3 of Itable I herein; ΔV_{F2} = ±0.1 V(pk); ΔI_{R1} = 5 μ A dc lor 100% from the initial value, whichever is greater.	Not applicable

^{1/} Surge shall precede thermal response. These tests shall be performed anytime after screen 3 and before screen 9.

 $[\]frac{2}{3}$ I_{R1} measurement shall not be indicative of an open condition. $\frac{3}{7}$ PDA of 13 shall apply to screen 11 for JANTX and JANTXV.

^{4.3.1 &}lt;u>Surge current</u>. Surge current, see MIL-STD-750, method 4066. I_0 = 0; $V_{RM}(W)$ = 0; I_{FSM} = 325; six surges; T_A = 25°C. One surge per minute maximum. t_p = 8.3 ms.

^{4.3.2} Thermal response (ΔV_F measurements). The ΔV_F measurements shall be performed in accordance with MIL-STD-750, method 3101. The ΔV_F conditions and maximum V_F limit shall be derived by each vendor. The chosen ΔV_F measurement and conditions for each device in the qualification lot shall be submitted in the qualification report and a thermal response curve shall be plotted. The chosen ΔV_F value shall be considered final after the manufacturer has had the opportunity to test five consecutive lots. $t_p=250$ ms. Heating current (I_H) \geq rated I_0 .

4.3.3 Power burn-in. Power burn-in conditions are as follows:

MIL-STD-750, method 1038, test condition B. $T_C = 150^{\circ}C$, f = 60 Hz; $I_O = 12$ A dc (see 4.5.1); $V_R = Rated\ V_R(pk)$ (see 1.4).

- 4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-S-19500.
- 4.4.1 Group A inspection. Group A inspection shall be conducted in accordance with MIL-S-19500, and table I herein. End-point electrical measurements shall be in accordance with the applicable steps of table V herein.
- 4.4.2 Group B inspection. Group B inspection shall be conducted in accordance with the conditions specified for subgroup testing in table IVa (JANS) and table IVb (JANTX and JANTXV) of MIL-S-19500, and tables IIa and IIb herein. Electrical measurements (end points) and delta requirements shall be in accordance with the applicable steps of table V herein.
- 4.4.3 <u>Group C inspection</u>. Group C inspection shall be conducted in accordance with the conditions specified for subgroup testing in table V of MIL-S-19500, and table III herein. Electrical measurements (end points) and delta requirements shall be in accordance with the applicable steps of table V herein.
- 4.5 Methods of inspection. Methods of inspection shall be as specified in appropriate tables and as follows.
- 4.5.1 <u>Burn-in and steady-state operation life tests</u>. These tests shall be conducted with a half-sine waveform of the specified peak voltage impressed across the diode in the reverse direction followed by a half-sine waveform of the specified average rectifier current. The forward conduction angle of the rectified current not be greater than 180 degrees nor less than 150 degrees.
- 4.5.2 DC intermittent operation life. A cycle shall consist of an "on" period, when power is applied suddenly, not gradually, to the device for the time necessary to achieve a delta case temperature of 85°C +15°C, -5°C, followed by an "off" period, when the power is suddenly removed, for cooling. Auxiliary (forced) cooling is permitted during the off period only. 30 s \leq theating \leq 60 s. P = VF X IF or P = VFPK X IAV if using sine wave current. DC full wave current (or equivalent half sine wave current) shall be used for the power required during the on period. Within the time interval of 50 cycles before to 500 cycles after the termination of the test, the sample units shall be removed from the specified test conditions and allowed to reach room ambient conditions. Specified end-point measurements for qualification and quality conformance inspection shall be completed within 96 hours after removal of sample units from the specified test conditions. Additional readings may be taken at the discretion of the manufacturer.

TABLE I. Group A inspection.

		MIL-STD-750]		Limits		
Inspection	 Method 	Conditions	† LTPD	Symbol	Min	Max	TUnit
Subgroup 1	<u> </u>				† 	j	
Visual and mechanical inspection	2071 						
Subgroup 2					}		
Forward voltage	4011	 I _F = rated I _{FSM}		V _{F1}		2.5	V dc
Forward voltage 	4011 - 	lif = 38 A(pk) pulse, pulse width = 8.5 ms, duty cycle = 2% maximum		V _{F2}		1.35	V(pk)
Reverse current	4016	DC method, V _R = Rated V _R (dc) (see 1.4)		I _{R1}		5	μA dc
Subgroup 3							
High temperature operation		T _C = 150°C		•			
Reverse current	4016	DC method, V _R = Rated V _R (see 1.4)		I _{R2}		1	mA dc
Low temperature operation		T _C = -65°C					
Reverse current	4026	 DC method, V _R = Rated V _R (see 1.4)		I _{R3}		1	mA dc
Subgroups 4 and 5		\SEC 1.4/] -	! 		
Not applicable							
Subgroup 6							
Not applicable							

 $[\]underline{1}$ / For LTPD numbers, see MIL-S-19500.

TABLE IIa. Group B inspection for JANS devices.

	MIL-STD-750		Qualification and	Small lot		
Inspection	ļ	T	llarge lot quality	quality confor-		
1	Method	Conditions	conformance inspec- tion LTPD <u>1</u> /	n/c 1/		
Subgroup 1						
Physical dimensions	2066	 See figure 1	! !			
Subgroup 2 2/	İ	! ! !	[]]			
Solderability	2026	! 	! 			
Resistance to solvents	1022	! 				
Subgroup 3	<u> </u> 					
Thermal shock (temperature cycling)	1051		I 			
Surge current	4066 - -	$ \begin{array}{llllllllllllllllllllllllllllllllllll$				
Hermetic seal	1071]		
Fine leak Gross leak						
Electrical measurements		See table V, steps 1, 2, 4, and 5				
Decap-internal visual (design verification)	2075					
Die shear	2017					
Subgroup 4			 			
DC intermittent operation life		.25 rated I _O < I _O applied < rated I _O (see 4.5.2); 2,000 cycles	5	12/0 		
Electrical measurements		See table V, steps 1, 2, 4, and 5				

See footnotes at end of table.

TABLE IIa. Group B inspection for JANS devices - Continued.

	MIL-STD-750		Qualification and	Small lot quality confor-		
Inspection	 Method 	Conditions	conformance inspec- tion LTPD <u>1</u> /	mance inspection $n/c \frac{1}{2}$		
Subgroup 5] 		-			
Accelerated steady- state operation life	1027	$ I_F =4$ A dc; $ V_R =$ Rated $ V_R $ (see 1.4), $ T_A =$ 125°C; or adjusted $ T_A =$ 125°C; or adjusted $ T_A =$ 125°C the chosen $ T_A =$ 1275°C (see 4.5.1), $ T_A =$ 1275°C (see 4.5.1),				
Electrical measurements	 	 See table V, steps 3, 6, and 7				
Subgroup 6		! ! !				
Thermal resistance	3101	 See 1.5 	1	 		

 $[\]underline{1}$ / For LTPD numbers, see MIL-S-19500.

TABLE IIb. Group B inspection for JANTX and JANTXV devices.

		MIL-STD-750	Qualification and	Small lot
Inspection	 Method 	Conditions	llarge lot quality conformance inspec- tion LTPD 1/	quality confor- mance inspection n/c <u>1</u> /
Subgroup 1 2/				
Solderability	l 2026	 	[Î I
Resistance to solvents	1022			
Subgroup 2			!	<u> </u>
Thermal shock (temperature cycling)	1051		 	
Surge current	4066	T _C = 150°C; i _f (surge) = 240 A; I _O = 12 A dc; six surges; 1 surge per minute maximum V _R = Rated V _R (see 1.4) t _p = 8.3 ms		
Hermetic seal	1071		[[
Fine leak Gross leak				
Electrical measurements		! See table V, steps 1, 2, and 4		
Subgroup 3 2/] 	
DC intermittent operation life 	1037	.25 rated $I_0 \le I_0$ applied \le rated I_0 (see 4.5.2); 2,000 cycles		
Electrical measurements		See table V, steps 1, 2, and 4		
Steady-state DC blocking life	1038 or 1049	Condition A; 340 hrs		
Electrical measurements	· ·	See table V, steps, 1 and 2		
Subgroup 4				
Decap internal visual (design verification)	2075			
Subgroup 5			·	
Not applicable	ļ			
Subgroup 6	į			
High temperature (nonoperating)	1032	T _A = 200°C minimum		
 Electrical measurements	 	See table V, steps 1 and 2		
1/ For LTPD numbers, see	MIL-S-1	9500.		<u></u>

 $[\]underline{2}$ / A separate sample may be pulled for each test.

TABLE III. Group C inspection.

	MIL-STD-750		Qualification and	Small lot
Inspection	 Method	 Conditions	large lot quality conformance inspec- tion LTPD <u>1</u> /	quality confor- mance inspection n/c <u>1</u> /
Subgroup 1				
 Physical dimensions	2066	 See figure 1		<u> </u>
Subgroup 2		! ! !		
 Thermal shock (glass strain)	1056 	 Test condition B 	 	 -
 Terminal strength (tension)	2036	Test condition A, Weight = 10 lbs, t = 15 s	 	
Bending stress	 	Test condition F, method B, Weight = 5 lbs, t = 15 s		
Seal torque		 Test condition D1, Torque = 10 oz-in, t = 15 s	! 	
Stud torque		 Test condition D2, Torque = 15 lb-in, t = 15 s	 	
 Hermetic seal	1071]	
Fine leak Gross leak			 	
Moisture resistance	1021		! !	
Electrical measurements		 See table V, steps 1, 2, and 4 (JANTX and JANTXV), Steps 1, 2, 4, and 5 (JANS)		
Subgroup 3			<u> </u>	
Shock .	2016] 	
Vibration, variable frequency	2056		 	
Constant acceleration	2006			
Electrical measurements		See table V, steps 1 and 2	; 	
Subgroup 4	ļ			
Salt atmosphere (corrosion)	1041		 	

See footnote at end of table.

TABLE III. Group C inspection - Continued.

			Qualification and large lot quality	Small lot quality confor-	
Inspection	 Method 	Conditions	conformance inspec- tion LTPD <u>1</u> / 	mance inspection $n/c \frac{1}{2}$	
Subgroup 5	<u> </u>				
N/A	 		 		
Subgroup 6		 	5	12/0	
DC intermittent operation life	1037	.25 rated I _O < I _O I _O			
Electrical measurements 	 	See table V, steps 3, 4, 5, land 7 (JANS), and steps 3, 4, land 7 (JANTX, JANTXV)			

^{1/} For LTPD numbers, see MIL-S-19500.

TABLE IV. Group E inspection (all quality levels) for qualification only.

	ļ	MIL-STD-750	[Qualification and	Small lot
Inspection			conformance inspec-	quality confor- mance inspection
	Method	Conditions	tion LTPD	n/c'
Subgroup 1			10	6/0
Thermal shock (glass strain)	1056	0°C to 100°C, 100 cycles	 	
Hermetic seal	1071		1] [
Electrical measurements		See table V, steps 2, 3, and 4] 	
Subgroup 2			5	12/0
Steady-state DC blocking life	1038 or 1049	Condition A; 1,000 hrs		
Electrical measurements		See table V, steps 3, 6, and 7	.	
Subgroup 3				
DPA 		Photos of cross sections shall be submitted in the qualification report. Vendors shall retain duplicate photos.	3/0	1/0
Subgroup 4			10	6/0
Thermal resistance	3101	See 1.5		
Subgroup 5				
Barometric pressure (reduced) 	1001	Hg = rated Hg; t = 60 s, Voltage during test		
1N1202A				
1N1204A 1N1206A		400 V dc 600 V dc	 	
1N3671A	į	800 V dc 1000 V dc	 	
		While the test is being performed, Ip shall be monitored and shall not		
		exceed group A limits.	 	İ

TABLE V. Groups A, B, and C electrical end-point measurements.

1	T		MIL-STD-750		Lin	nits	1
Cton	Imanaaktan	 	· · · · · · · · · · · · · · · · · · ·				<u>i</u>
Step	Inspection	Method	Conditions	Symbol	Min	Max	T Unit
1.	 Forward voltage 	4011	if = 38 A(pk) (pulse); pulse width = 8.5 ms duty cycle = 2% maximum	V _{F2}		1.35	 V(pk)
2.	Reverse current	4016	 DC method V _R = Rated V _R (dc) (see 1.4)	I _{R1}		5	μA dc
3. 	 Forward voltage 	4011	lif = 38 A(pk) (pulse); pulse width = 8.5 ms duty cycle = 2% maximum	V _{F2}		1.4	V(pk)
4.	 Thermal response	3101	 See 4.3.2	ΔV _F	! 		mV dc
5. 	Forward voltage 	4011	I _F = 50 mA dc	ΔVF3	from p post i life a shock	dc m chang revious ntermit nd ther measure (JANS o	to tent mal ment
6. 	 Reverse current - 	4016	 DC method, V _R = Rated V _R (dc) (see 1.4)	ΔI _{R1} <u>1</u> /	(which greate from i	r 5 μA, ever is r) chan nitial A readi	ge
7.	 Reverse current	 4016 	DC method, V _R = Rated V _R (dc) (see 1.4)	I _{R4}	 - - 	 10 	μΑ dc

 $[\]underline{1}$ / Devices which exceed the group A limits for this test shall be rejected.

- PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-S-19 $\overline{500}$.
 - 6. NOTES

(This section contains information of a general or explanatory nature that may be helpful, but is not mandatory.)

- 6.1 Notes. The notes specified in MIL-S-19500 are applicable to this specification.
- 6.2 Acquisition requirements. Acquisition documents must specify the following:
- a. Title, number, and date of the specification.
- b. Issue of DODISS to be cited in the solicitation, and if required, the specific issue of individual documents referenced (see 2.1.1).
- c. Lead finish may be specified (see 3.3.1).
- 6.3 <u>Substitution information</u>. Devices covered by this specification are substitutable for the manufacturer's and user's part numbers. This information in no way implies that manufacturer's part numbers are suitable as a substitute for the military Part or Identifying Number (PIN).

Military Part or Identifying Number	Manufacturer's CAGE code 	Manufacturer's and user's part number
1N1 204A	CDK F	S13001 935A486-1
1N12O4RA	CDKF I	S13002 935A486-2
ı		
1		

6.4 Changes from previous issue. Marginal notations are not used in this revision to identify changes with respect to the previous issue due to the extensiveness of the changes.

CONCLUDING MATERIAL

Custodians:

Army - ER Navy - EC Air Force - 17 NASA - NA

Review activities:

Army - AR, MI NASA - MSFC - EGO2

Air Force - 11, 19, 85, 99

DLA - ES

User activities:

Army - SM Navy - AS, CG, MC, OS, SH

Preparing activity: Navy - EC

Agent:

DLA - ES

(Project 5961-1066)